

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
OSAMU MUNEKATA	07/16/2021
MASATO SHIRATORI	07/16/2021
RECEIVING PARTY DATA	
Name:	SENJU METAL INDUSTRY CO., LTD.
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City:	ADACHI-KU, TOKYO
State/Country:	JAPAN
Postal Code:	120-8555
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17426137
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DATE SIGNED:	07/28/2021
Total Attachments: 3	
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P3138W005
DSO 1320
A 1/3

Docket No. _____

ASSIGNMENT

WHEREAS, (I/we), (1) Hiroyoshi KAWASAKI, (2) Osamu MUNEKATA, and (3) Masato SHIRATORI a citizen of Japan, residing at (1) Tokyo, Japan,
(2) Tokyo, Japan, (3) Tokyo, Japan, have invented a

SOLDER ALLOY, SOLDER POWDER, AND SOLDER JOINT

for which (I/we) have executed application papers for U.S. patent application filed herewith; and

WHEREAS, SENJU METAL INDUSTRY CO., LTD. having a place of business located at 23, Senju-Hashido-cho, Adachi-ku, Tokyo 120-8555 Japan, is desirous of acquiring the exclusive right, title and interest in and to said invention and in and to the Letters Patent to be granted and issued therefor in the United States of America and its territories and possessions, and all countries foreign thereto;

NOW, THEREFORE, for a valuable consideration, the receipt of which is hereby acknowledged, (I/we), (1) Hiroyoshi KAWASAKI, (2) Osamu MUNEKATA, and (3) Masato SHIRATORI, do sell, assign, transfer and set over unto the said SENJU METAL INDUSTRY CO., LTD., its successors and assigns, the full and exclusive right, title and interest in and to said invention, and in and to any and all Letters Patent to be granted and issued therefor, not only for, to and in the United States of America, its territories and possessions, but also for, to and in all other countries including all priority rights under the International Convention; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said SENJU METAL INDUSTRY CO., LTD., its successors and assigns, in accordance with this Assignment.

P3138W0U5
DSO 1320
A 2/3

Docket No. _____

[ASSIGNMENT CONTINUATION]

Re: U.S. Patent Application entitled:

Inventor: Hiroyoshi KAWASAKI

WITNESS MY HAND at _____, this
(city, state, country)

_____, day of _____,
(date) (month) (year)

Name: Hiroyoshi KAWASAKI

Re: U.S. Patent Application entitled: **SOLDER ALLOY, SOLDER POWDER, AND SOLDER JOINT**

Inventor: Osamu MUNEKATA

WITNESS MY HAND at Tokyo, Japan, this
(city, state, country)

_____, 16th day of July, 2021
(date) (month) (year)

P3138W0US
DSO1320
A3/3

Docket No. _____

Osamu MuneKata
Name: Osamu MUNEKATA

Re: U.S. Patent Application entitled: SOLDER ALLOY, SOLDER POWDER, AND SOLDER JOINT

Inventor: Masato SHIRATORI

WITNESS MY HAND at Tokyo, Japan, this
(city, state, country)

16th day of July, 2021.
(date) (month) (year)

Masato Shiratori
Name: Masato SHIRATORI